
Semiconductor devices - Mechanical and climatic test methods - Part 6: Storage at high temperature (IEC 60749-6:2002)

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EUROPEAN STANDARD

EN 60749-6

NORME EUROPÉENNE

EUROPÄISCHE NORM

August 2002

ICS 31.080.01

Partly supersedes EN 60749:1999 + A1:2000 + A2:2001

English version

**Semiconductor devices -
Mechanical and climatic test methods
Part 6: Storage at high temperature
(IEC 60749-6:2002)**

Dispositifs à semiconducteurs -
Méthodes d'essais mécaniques
et climatiques
Partie 6: Stockage à haute température
(CEI 60749-6:2002)

Halbleiterbauelemente -
Mechanische und klimatische
Prüfverfahren
Teil 6: Lagerung bei hoher Temperatur
(IEC 60749-6:2002)

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This European Standard was approved by CENELEC on 2002-07-02. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Czech Republic, Denmark, Finland, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Luxembourg, Malta, Netherlands, Norway, Portugal, Slovakia, Spain, Sweden, Switzerland and United Kingdom.

CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

Foreword

The text of document 47/1603/FDIS, future edition 1 of IEC 60749-6, prepared by IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60749-6 on 2002-07-02.

This mechanical and climatic test method, as it relates to storage at high temperature, is a complete rewrite of the test contained in clause 2, chapter 3 of EN 60749:1999.

The following dates were fixed:

- latest date by which the EN has to be implemented
at national level by publication of an identical
national standard or by endorsement (dop) 2003-04-01
- latest date by which the national standards conflicting
with the EN have to be withdrawn (dow) 2005-07-01

Annexes designated "normative" are part of the body of the standard.
In this standard, annex ZA is normative.
Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 60749-6:2002 was approved by CENELEC as a European Standard without any modification.

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Annex ZA (normative)

Normative references to international publications with their corresponding European publications

This European Standard incorporates by dated or undated reference, provisions from other publications. These normative references are cited at the appropriate places in the text and the publications are listed hereafter. For dated references, subsequent amendments to or revisions of any of these publications apply to this European Standard only when incorporated in it by amendment or revision. For undated references the latest edition of the publication referred to applies (including amendments).

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60068-2-48	1982	Environmental testing Part 2: Tests - Guidance on the application of the tests of IEC 60068 to simulate the effects of storage	EN 60068-2-48	1999

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Première édition
First edition
2002-04

**Dispositifs à semiconducteurs –
Méthodes d'essais mécaniques et climatiques –**

**Partie 6:
Stockage à haute température**

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**Semiconductor devices –
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**Part 6:
Storage at high temperature**

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Commission Electrotechnique Internationale
International Electrotechnical Commission
Международная Электротехническая Комиссия

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For price, see current catalogue

INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SEMICONDUCTOR DEVICES –
MECHANICAL AND CLIMATIC TEST METHODS –****Part 6: Storage at high temperature****FOREWORD**

- 1) The IEC (International Electrotechnical Commission) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of the IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, the IEC publishes International Standards. Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. The IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
- 2) The formal decisions or agreements of the IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested National Committees.
- 3) The documents produced have the form of recommendations for international use and are published in the form of standards, technical specifications, technical reports or guides and they are accepted by the National Committees in that sense.
- 4) In order to promote international unification, IEC National Committees undertake to apply IEC International Standards transparently to the maximum extent possible in their national and regional standards. Any divergence between the IEC Standard and the corresponding national or regional standard shall be clearly indicated in the latter.
- 5) The IEC provides no marking procedure to indicate its approval and cannot be rendered responsible for any equipment declared to be in conformity with one of its standards.
- 6) Attention is drawn to the possibility that some of the elements of this International Standard may be the subject of patent rights. The IEC shall not be held responsible for identifying any or all such patent rights.

International Standard IEC 60749-6 has been prepared by IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47/1603/FDIS	47/1619/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This mechanical and climatic test method, as it relates to storage at high temperature, is a complete rewrite of the test contained in clause 2, chapter 3 of IEC 60749.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 3.

The committee has decided that the contents of this publication will remain unchanged until 2007. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

The contents of the corrigendum of August 2003 have been included in this copy.

SEMICONDUCTOR DEVICES – MECHANICAL AND CLIMATIC TEST METHODS –

Part 6: Storage at high temperature

1 Scope

The purpose of this part of IEC 60749 is to test and determine the effect on all semiconductor electronic devices of storage at elevated temperature without electrical stress applied. This test is considered non-destructive but should preferably be used for device qualification. If such devices are used for delivery, the effects of this highly accelerated stress test will need to be evaluated.

In general, this test of storage at high temperature is in conformity with IEC 60068-2-48 but, due to specific requirements of semiconductors, the clauses of this standard apply.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60068-2-48:1982, *Environmental testing – Part 2: Tests. Guidance on the application of the tests of IEC 68 to simulate the effects of storage*

[SIST EN 60749-6:2004](https://standards.iteh.ai/catalog/standards/sist/55284d04-7fa4-4ce4-81cb-824fc441247e/sist-en-60749-6-2004)

3 Test apparatus

The apparatus required for this test shall consist of a controlled temperature chamber capable of maintaining the specific temperature within ± 2 °C.

4 Procedure

The device under test shall be subjected to continuous storage at $+150^{+4}_{0}$ °C for $1\,000^{+72}_{0}$ h, except they shall be returned to room ambient conditions for interim electrical measurements.

4.1 Measurements

Unless otherwise specified, interim and final electrical measurements shall be completed within 96 h after removal of the devices from the specified test conditions. Intermediate measurements are optional unless otherwise specified.

The electrical measurements shall consist of parametric and functional tests specified in the applicable procurement document.